




<b>Form 1449 (Modified)</b>  <b>Information Disclosure</b>  <b>Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No. AFFYP007X1C1 Application No.:09/607,536 Inventor: Earl A. Hubbell et al. Group: 1655 Filing Date: June 29, 2000
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### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	5,571,639	11/5/96	Hubbell et al.	430	5	5/24/94
	B						
	C						
	D						
	E						
	F						

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	G	0 464 414	1/8/92	EP				
	H	0 799 897	10/8/97	EP				
	I							
	J							
	K							

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	L	L.A. Colom et al., "Defect Data Analysis in Integrated Circuit Manufacturing" IBM Technical Disclosure Bulletin, IBM Corp., New York, US. Vol. 18, no. 4, September 1975, pages 1059-1060
	M	
	N	
Examiner 		Date Considered 5/8/02

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.